

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Canceled).

Claim 2 (Currently Amended): A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a ~~conductor~~ wiring layer formed on one surface thereof, the process comprising:

a first step to form ~~forming~~ a via hole in the base material having the ~~conductor~~ wiring layer by performing laser irradiation at least from the other surface side of the base material;

a second step to deposit a first electroplating by using the wiring layer as an electrode until the core material protruding from the inner wall surface of the via hole is covered;

a third step to form ~~forming~~ an electroless plating layer in close contact with an inner wall surface of the via hole and without contacting the core material ~~after deposition of a plating until the core material exposed on the inner wall surface of the via hole is covered by using the conductor layer as an electrode;~~ and

a fourth step to deposit ~~depositing~~ a second electroplating ~~plating again~~ by using the conductor layer as an electrode to cover the electroless plating layer ~~to thereby form a conductor part in the via hole,~~

wherein three layers in order from a wiring-layer side: the first electroplating layer; the electroless plating layer; and the second electroplating layer, are stacked in the via hole to thereby form a conductor part.

Claim 3 (Currently Amended): A process for producing an electronic component according to Claim 2, wherein a laser beam is applied onto the base material with a power of

the laser beam adjusted in view of a difference in melting temperature between resin forming the base material and the core material such that the core material is caused to protrude from the inner wall surface of the via hole, through laser irradiation to thereby form an anchor structure with respect to the conductor part.

Claim 4 (Canceled).

Claim 5 (Currently Amended): A process for producing an electronic component according to any one of claims 2 ~~through 4~~ and 3, wherein the core material is formed of glass cloth.

Claims 6-13 (Canceled).